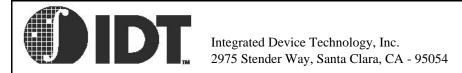


Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

TROB	Je 1/1 No elbi	CHANGENGE	TICE (I C		
PCN #: A-0310-01	DATE: 10/10/20	003 MEANS OF DISTI	INGUISHING CHANGED DEVICES:		
Product Affected: Not Appli	cable	Product Mark	"G" character in	the package code	
(New Pro	duct Offering)	☐ Back Mark	(New ordering l	Part # for Green Parts)	
		☐ Date Code			
Date Effective: 10/10/2003		□ Other			
Contact: Geoffrey Cortes		·			
Title: Corporate QA / Reliabi	lity Manager	Attachment::	¥ Yes	☐ No	
Phone #: (408) 492- 8321					
Fax #: (408) 727-2328	•				
E-mail: <u>Geoffrey.Cortes@idt.co</u>	<u>om</u>				
DESCRIPTION AND PURPOSE OF CHANGE:					
☐ Die Technology					
☐ Wafer Fabrication Process					
Assembly Process In order to support customer's lead free applications, IDT has been proactively developing					
□ Matarial	Equipment and qualifying Green Products. Green products are in compliance with industry standard fo				
□ Testine	lead, halogen and antimony contents. Green parts can be identified by the package code that				
☐ Manufacturing Site	s marked on the part. The	e package code will incorp	oorate an extra "G'	' character.	
□ Data Sheet					
Other	Please see attachment for additional details				
RELIABILITY/QUALIFICATION SUMMARY: Reliability test data is available upon request.					
Renability test data is available	; upon request.				
CUSTOMER ACKNOWLEDGMENT OF RECEIPT:					
		of this change Please use th	ne acknowledgeme	ent below or F-Mail	
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice					
it will be assumed that this change is acceptable.					
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory					
on the earlier version has been depleted.					
	<u>-</u>				
Customer:		☐ Approval for	shipments prio	or to effective date.	
		T. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1.			
Name/Date:		E-Mail Address:			
Title:	Phone# /Fax# :				
		I none / I dx// .			
CUSTOMER COMMENTS:					
IDT ACKNOWLEDGMENT O	F RECEIPT:				
		D 4 mm			
RECD. BY:		DATE:			



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: A-0310-01

PCN Type: Green product offering

Detail of Change:

In order to support customer's lead free applications, IDT will be offering Green products in phases. Green parts are in compliance with industry standard for lead, halogen, and antimony contents. Initially, samples and low volume production will be offered for selective devices/packages.

Green products will have different ordering part numbers. Green parts can be identified by the package code that is marked on the part. The package code will incorporate an extra "G" character. For example: PY20 is the package code for SSOP20 products. PYG20 is the package code for Green SSOP product. Hence the ordering part number for conventional device type IDT74FCT3244PY is changed to IDT74FCT3244PYG for green part.

Green Parts are assembled using material sets that are selected for their superior properties and low moisture absorption. Green parts are qualified using JEDEC-Std-020B for moisture sensitivity classification with peak reflow temperature of 260°C. Please see below the recommended 260°C reflow profile. Reliability tests include Auto Clave, HAST, Temperature Cycle, Solderability, Storage tests, and tin whisker inspection.

Reliability test data is available upon request.

For the solder finish/material, IDT uses pure matte tin plating finish for the leaded and MLF packages and Sn/Ag/Cu solder balls for the array packages. These materials are industry preferred materials and are chosen for their reliability, availability and lower cost.

IDT has a comprehensive infrastructure in place and will continue to support the existing conventional product offerings (leads/balls containing lead) as long as demand supports the manufacturing infrastructure.

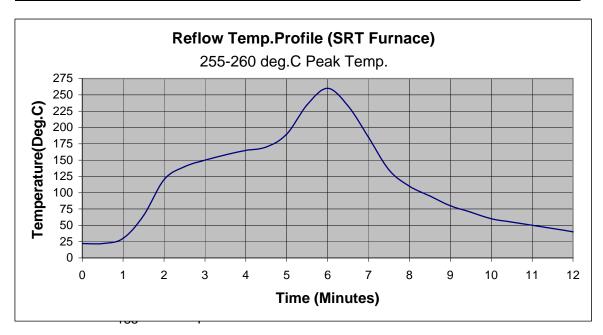
Please contact your local sales representative for sample and production availability.

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: A-0310-01

IDT 260°C Reflow Profile

Parameter	Value	
Max. Ramp-up Rate (200°C to Peak)	3°C/second	
Preheat Time (175°C ± 25°C)	60-180 seconds	
Time Maintained Above 217°C	60-150 seconds	
Time within 5°C of actual Peak Temp	20-40 seconds	
Peak Temperature	255°C +5/-0°C	
Max. Ramp-Down Rate	6°C/second	
Time 25°C to Peak Temperature	8 minutes max.	



NEMI recommendation